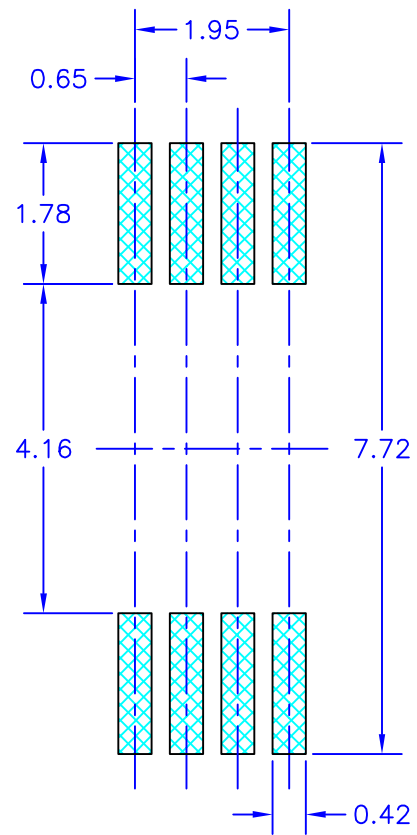
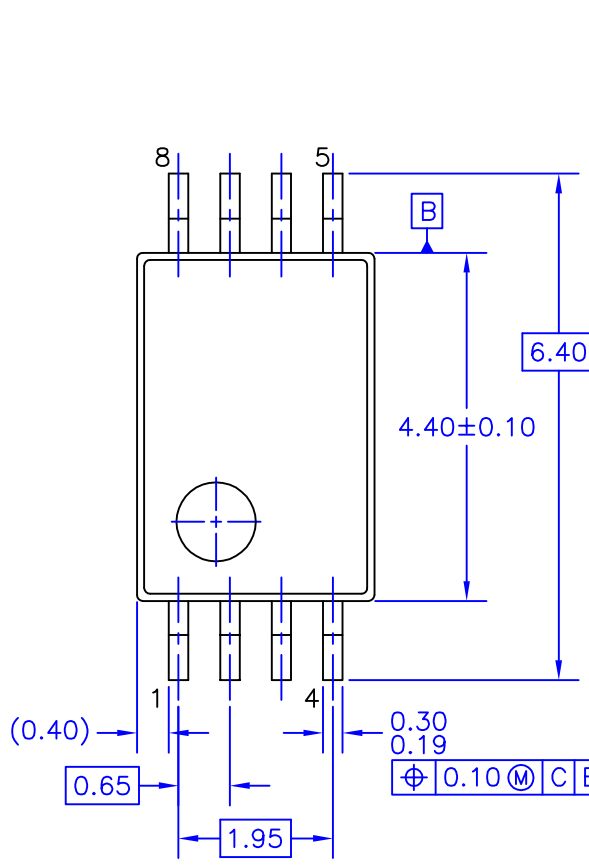
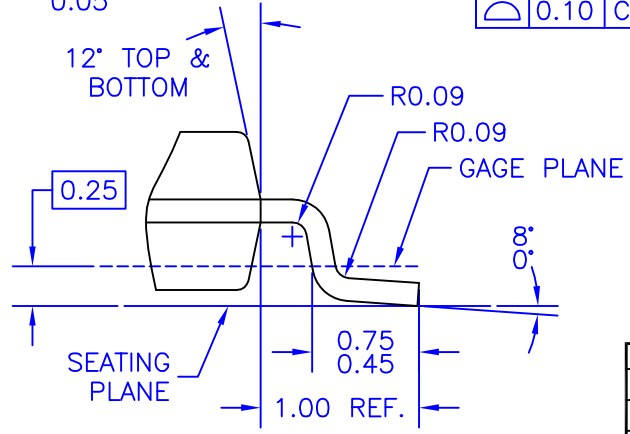
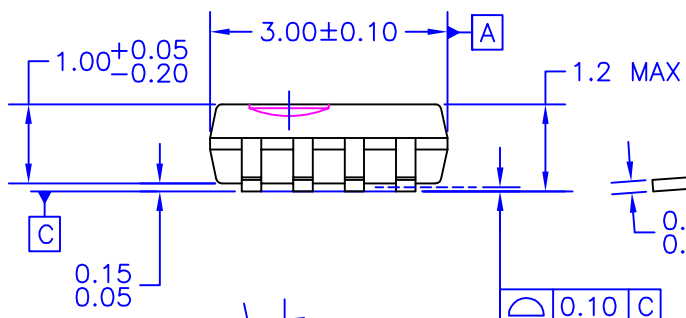


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REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11077	09/01/95	MS/
B	REDRAW AS PER NEW DRAWING TEMPLATE. CHANGE TOLERANCE STYLE FROM SYMMETRICAL TO LIMITS.	06299	09/15/99	MRG/HA



LAND PATTERN RECOMMENDATION



DETAIL A
SCALE: 2X

NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MO-153, ISSUE E, VARIATION AA, DATED OCTOBER 1997.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC08REVB

APPROVALS	DATE	 CEBU PHILIPPINES
DRAWN: J. GOMEZ	JAN.13,2000	
ORDERED: M. GESTOLE / M. TUNULAK		
APPROVED: G.S. BAJE		
C.N. TANGPUZ		8LD, TSSOP, JEDEC MO-153, 4.4MM WIDE
PROJECTION	SCALE	REV
	1:1	NA
FORMERLY: N/A	SIZE	MKT-MTC08
		REV B
		SHEET: 1 OF 1